

SEMICONDUCTOR TM

# FQD3N60 / FQU3N60 600V N-Channel MOSFET

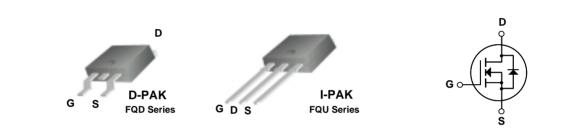
## **General Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply.

### Features

- 2.4A, 600V,  $R_{DS(on)} = 3.6\Omega @V_{GS} = 10 V$  Low gate charge ( typical 10 nC)
- Low Crss (typical 5.5 pF)
- · Fast switching
- 100% avalanche tested
- Improved dv/dt capability



# Absolute Maximum Ratings T<sub>c</sub> = 25°C unless otherwise noted

| Symbol                            | Parameter   |          | FQD3N60 / FQU3N60 | Units |
|-----------------------------------|---|----------|-------------------|-------|
| V <sub>DSS</sub>                  | Drain-Source Voltage  |          | 600               | V     |
| I <sub>D</sub>                    | Drain Current - Continuous ( $T_c = 25^{\circ}C$ )<br>- Continuous ( $T_c = 100^{\circ}C$ ) |          | 2.4               | А     |
|                                   |   |          | 1.5               | А     |
| I <sub>DM</sub>                   | Drain Current - Pulsed  | (Note 1) | 9.6               | А     |
| V <sub>GSS</sub>                  | Gate-Source Voltage   |          | ± 30              | V     |
| E <sub>AS</sub>                   | Single Pulsed Avalanche Energy (Note 2)   |          | 200               | mJ    |
| I <sub>AR</sub>                   | Avalanche Current (Note 1)  |          | 2.4               | А     |
| E <sub>AR</sub>                   | Repetitive Avalanche Energy (Note 1)  |          | 5.0               | mJ    |
| dv/dt                             | Peak Diode Recovery dv/dt (Note 3)  |          | 4.5               | V/ns  |
| P <sub>D</sub>                    | Power Dissipation ( $T_A = 25^{\circ}C$ ) *   |          | 2.5               | W     |
| -                                 | Power Dissipation ( $T_C = 25^{\circ}C$ )   |          | 50                | W     |
|                                   | - Derate above 25°C   | 0.4      | W/°C              |       |
| T <sub>J</sub> , T <sub>STG</sub> | Operating and Storage Temperature Range   |          | -55 to +150       | °C    |
| Τ <sub>L</sub>                    | Maximum lead temperature for soldering purposes,<br>1/8" from case for 5 seconds            |          | 300               | °C    |

# **Thermal Characteristics**

| Symbol          | Parameter                                 | Тур | Max | Units |
|-----------------|---|-----|-----|-------|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case      |     | 2.5 | °C/W  |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient * |     | 50  | °C/W  |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient   |     | 110 | °C/W  |

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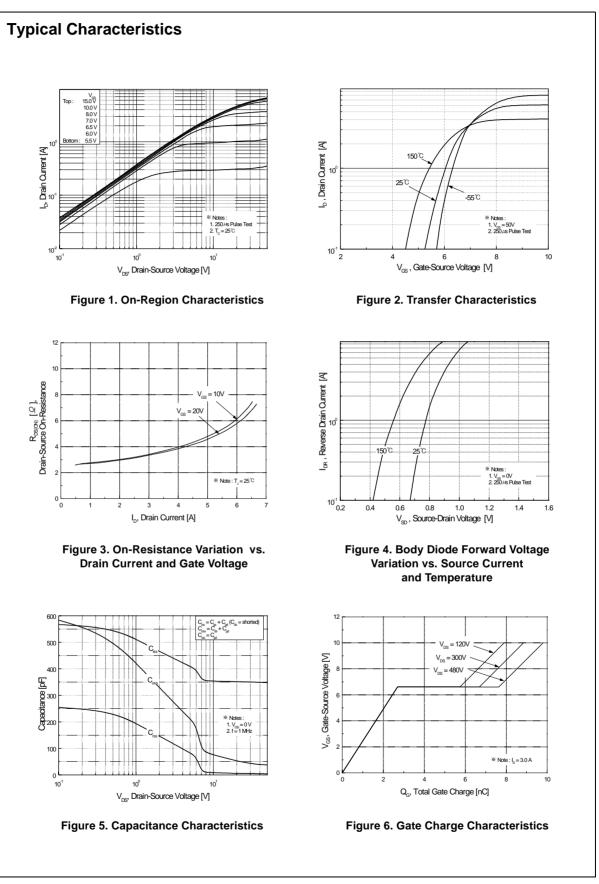
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| Symbol  | Parameter   | Test Conditions  | Min | Тур             | Max        | Units    |
|---|---|--|-----|-----------------|------------|----------|
| Off Cha   | aracteristics   |  |     |                 |            |          |
| BV <sub>DSS</sub>   | Drain-Source Breakdown Voltage  | $V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$                                  | 600 |                 |            | V        |
| ΔΒV <sub>DSS</sub><br>/ ΔT <sub>J</sub>   | Breakdown Voltage Temperature<br>Coefficient  | $I_D = 250 \ \mu$ A, Referenced to 25°C  |     | 0.6             |            | V/°C     |
| IDSS  | Zerra Orata Malta era Deraia Orana at   | $V_{DS} = 600 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$                                   |     |                 | 10         | μA       |
|   | Zero Gate Voltage Drain Current   | V <sub>DS</sub> = 480 V, T <sub>C</sub> = 125°C  |     |                 | 100        | μA       |
| I <sub>GSSF</sub>   | Gate-Body Leakage Current, Forward  | $V_{GS} = 30 \text{ V}, \text{ V}_{DS} = 0 \text{ V}$                                    |     |                 | 100        | nA       |
| I <sub>GSSR</sub>   | Gate-Body Leakage Current, Reverse  | $V_{GS} = -30 \text{ V}, \text{ V}_{DS} = 0 \text{ V}$                                   |     | -               | -100       | nA       |
| On Cha  | aracteristics   |  |     |                 |            |          |
| V <sub>GS(th)</sub>   | Gate Threshold Voltage  | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$   | 3.0 |                 | 5.0        | V        |
| R <sub>DS(on)</sub>   | Static Drain-Source<br>On-Resistance  | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.2 A   |     | 2.8             | 3.6        | Ω        |
| 9fs   | Forward Transconductance  | $V_{DS} = 50 \text{ V}, I_D = 1.2 \text{ A}$ (Note 4)                                    |     | 2.4             |            | S        |
| C <sub>iss</sub><br>C <sub>oss</sub>  | Input Capacitance Output Capacitance  | $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$<br>f = 1.0 MHz                            |     | 350<br>50       | 450<br>65  | pF<br>pF |
| C <sub>oss</sub>  | Output Capacitance  |  |     | 50              | 65         | pF       |
| C <sub>rss</sub>  | Reverse Transfer Capacitance  |  |     | 5.5             | 7.5        | pF       |
| Switchi   | ing Characteristics   |  |     |                 |            |          |
| t <sub>d(on)</sub>  | Turn-On Delay Time  | y = 200 y = 2.0 A  |     | 10              | 30         | ns       |
| t <sub>r</sub>  | Turn-On Rise Time   | $V_{DD} = 300 \text{ V}, \text{ I}_{D} = 3.0 \text{ A},$<br>R <sub>G</sub> = 25 $\Omega$ |     | 30              | 70         | ns       |
| t <sub>d(off)</sub>   | Turn-Off Delay Time   | - KG - 20 32   |     | 20              | 50         | ns       |
| t <sub>f</sub>  | Turn-Off Fall Time  | (Note 4, 5)  |     | 30              | 70         | ns       |
| Qg  | Total Gate Charge   | V <sub>DS</sub> = 480 V, I <sub>D</sub> = 3.0 A,   |     | 10              | 13         | nC       |
| Q <sub>gs</sub>   | Gate-Source Charge  | $V_{GS} = 10 \text{ V}$  |     | 2.7             |            | nC       |
|   | Gate-Drain Charge   | (Note 4, 5)  |     | 4.9             |            | nC       |
| Q <sub>gd</sub>   | Gale-Drain Charge   |  |     |                 |            |          |
|   |   | nd Maximum Ratings   |     |                 |            |          |
| Drain-S   | Source Diode Characteristics an<br>Maximum Continuous Drain-Source Dio  |  |     |                 | 2.4        | A        |
| Drain-S   | Source Diode Characteristics a  | ode Forward Current  |     |                 | 2.4<br>9.6 | A        |
| <b>Drain-S</b><br>I <sub>S</sub><br>I <sub>SM</sub>   | Source Diode Characteristics an<br>Maximum Continuous Drain-Source Dio  | ode Forward Current  |     | <br><br>        |            |          |
| Q <sub>gd</sub><br>Drain-S<br>I <sub>S</sub><br>I <sub>SM</sub><br>V <sub>SD</sub><br>t <sub>rr</sub> | Source Diode Characteristics an<br>Maximum Continuous Drain-Source Dio<br>Maximum Pulsed Drain-Source Diode F | ode Forward Current  |     | <br><br><br>210 | 9.6        | А        |

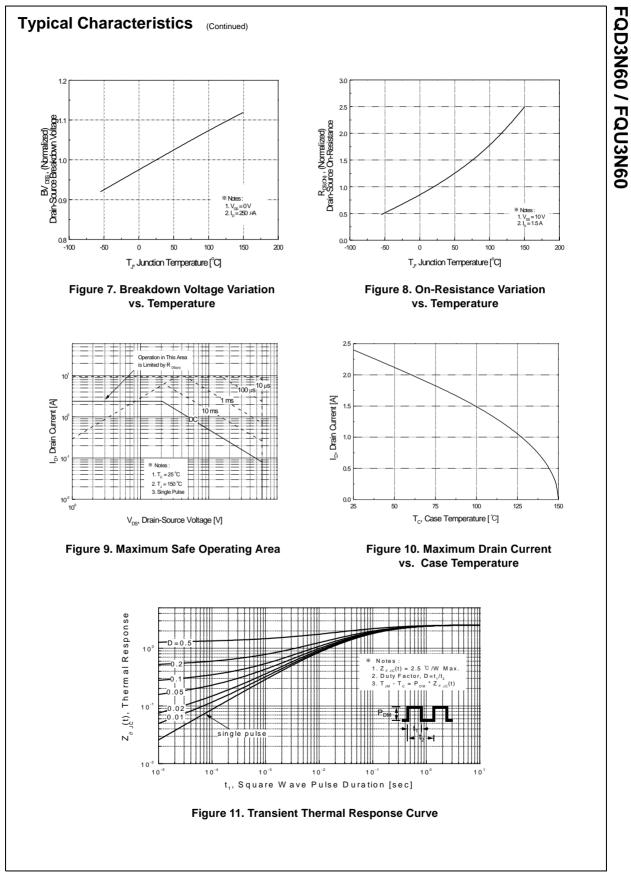
Notes: 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 64mH, I<sub>Ag</sub> = 2.4A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25  $\Omega$ , Starting T<sub>J</sub> = 25°C 3. I<sub>SD</sub>  $\leq$  3.0A, di/dt  $\leq$  200A/µs, V<sub>DD</sub>  $\leq$  BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C 4. Pulse Test : Pulse width  $\leq$  300µs, Duty cycle  $\leq$  2% 5. Essentially independent of operating temperature

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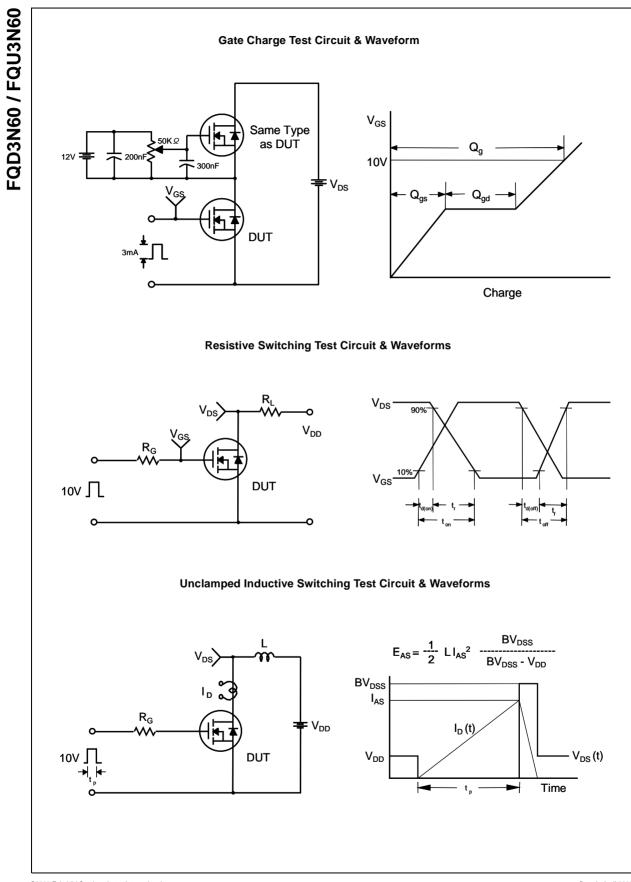
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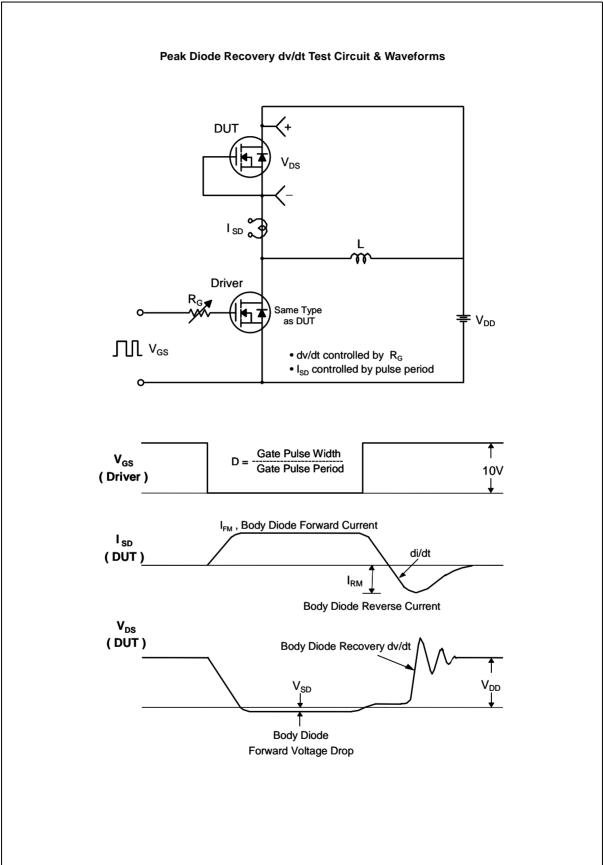
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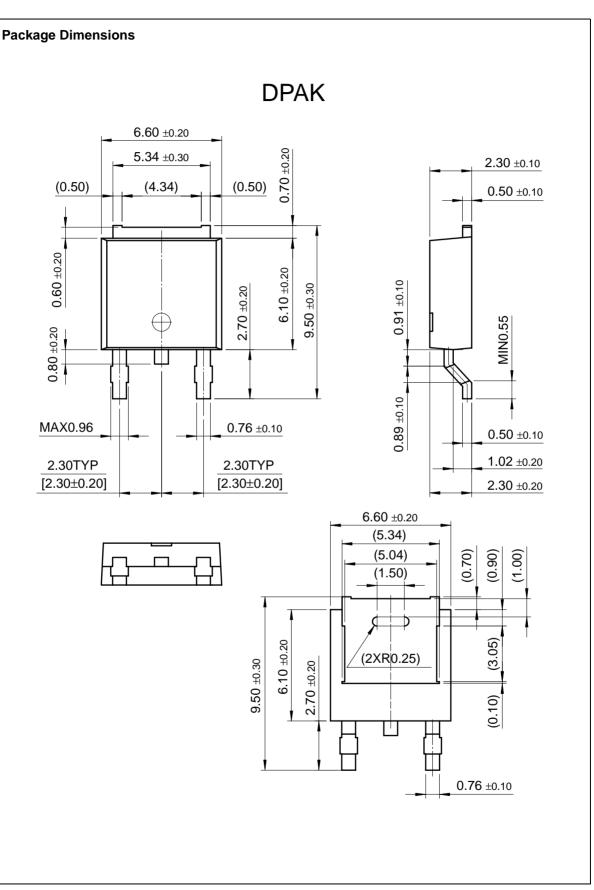


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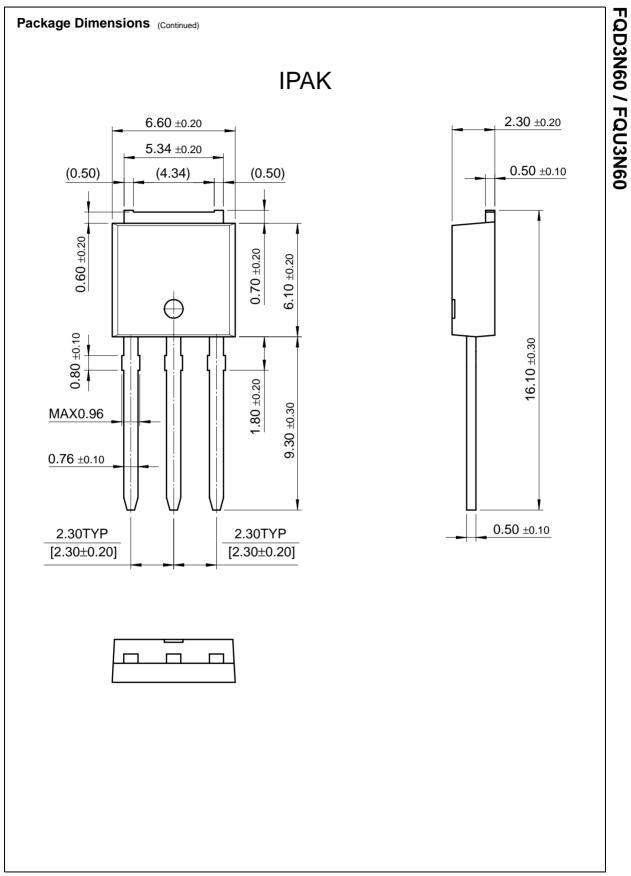


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| my Fairchild<br>company   | Features   |  |   |

- 2.4 A, 600 V. R<sub>DS(ON)</sub> = 3.6 Ω @ V<sub>GS</sub> = 10 V
  Low gate charge (typical 10 nC).
- Low Crss (typical 5.5 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

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Product status/pricing/packaging

| Product   | Product status  | Pricing* | Package type | Leads | Packing method |
|-----------|-----------------|----------|--------------|-------|----------------|
| FQD3N60TF | Full Production | \$0.62   | TO-252(DPAK) | 2     | TAPE REEL      |
|           |                 |          |              |       |                |

| FQD3N60TM          | Full Production | \$0.62 | TO-252(DPAK) | 2 | TAPE REEL |
|--------------------|-----------------|--------|--------------|---|-----------|
| * 1,000 piece Budg | etary Pricing   |        |              |   |           |

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